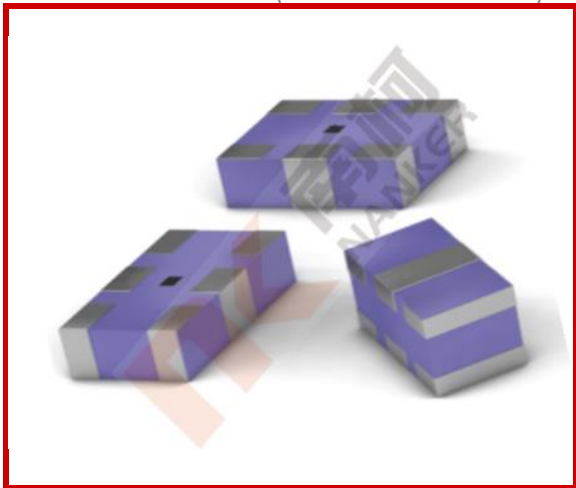


陶瓷共模扼流滤波器

DC Common Mode (Data Filter-Ceramic)



特性

Characteristics

紧凑型多层共模扼流圈/滤波器

Compact multilayer common mode choke/filter

基于LTCC的低损耗、高可靠性结构

LTCC based low-loss and highly reliable structure

超高速差分信号传输

Ultra-high-speed differential signal transmission

应用

Application

USB 3/4

USB 3/4

高速差分数据线

High speed differential datalines

显示端口

Display Port

产品品名介绍

Product Number Structure

DCCM03

0603

390

阻抗

Impedance Code

产品尺寸

Product Dimension

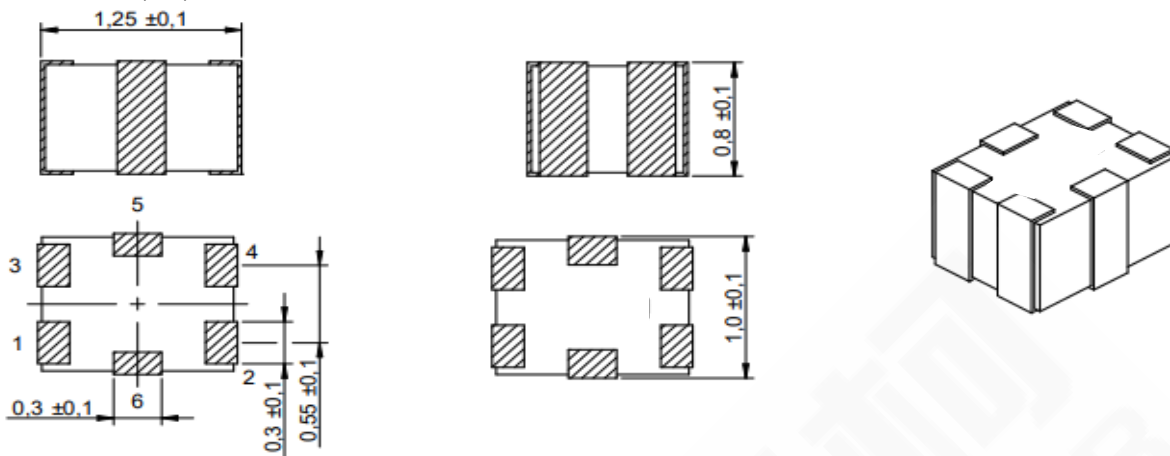
产品品名

Product Series Name



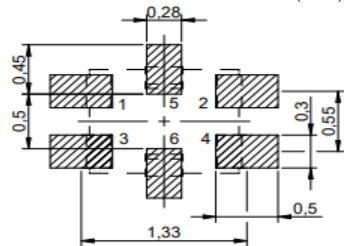
尺寸

Dimension (mm)



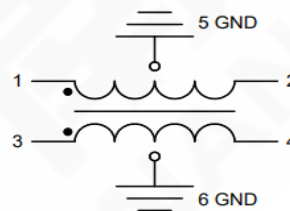
焊盘推荐

Land Pattern Recommended (mm)



示意图

Schematics



电性特性

Electrical Properties

| 型号 Part No. | 共模衰减 Common Mode Attenuation IL(scc2.1) (dB) | 测试条件 Test Condition IL(scc2.1) MHz | 阻抗 Impedance 100MHz (Ω) | 直流电阻 DCResistance DCRmax (Ω) | 温升电流 Rated Current I _R 40°C (mA) |
|-----------------|--|--|-------------------------------|------------------------------------|---|
| DCCM03-1210-2R0 | 30 | 2,450 | 2.00 | 2.50 | 300 |
| DCCM03-1210-1R6 | 20 | 2,450 & 5,500 | 1.60 | 2.500 | 300 |

测试状态

Test Condition

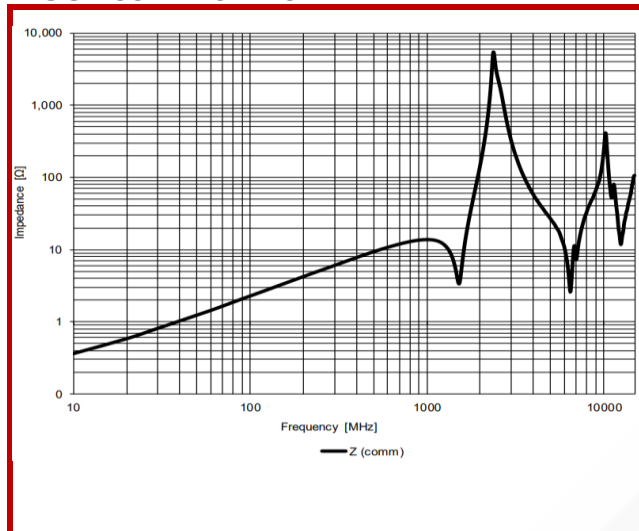
- ☆ 阻抗测试条件为 100MHz (25°C)
Impedance measure condition at 100MHz (25°C)
- ☆ 工作温度: -40°C ~ +85°C
Operating Temperature: -40°C ~ +85°C



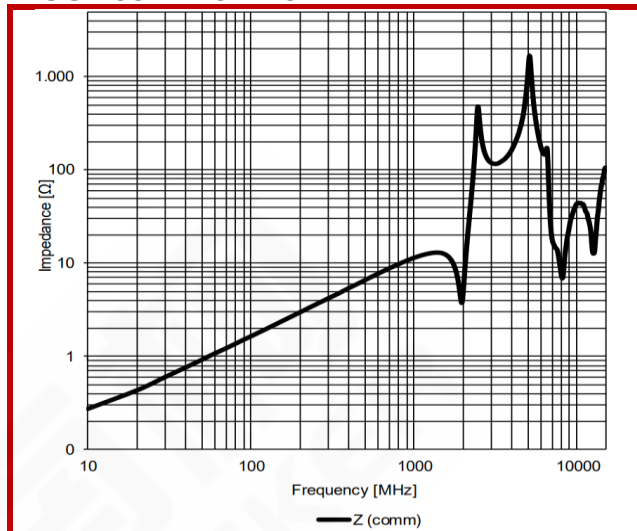
典型阻抗特性

Typical Impedance Characteristics

DCCM03-1210-2R0



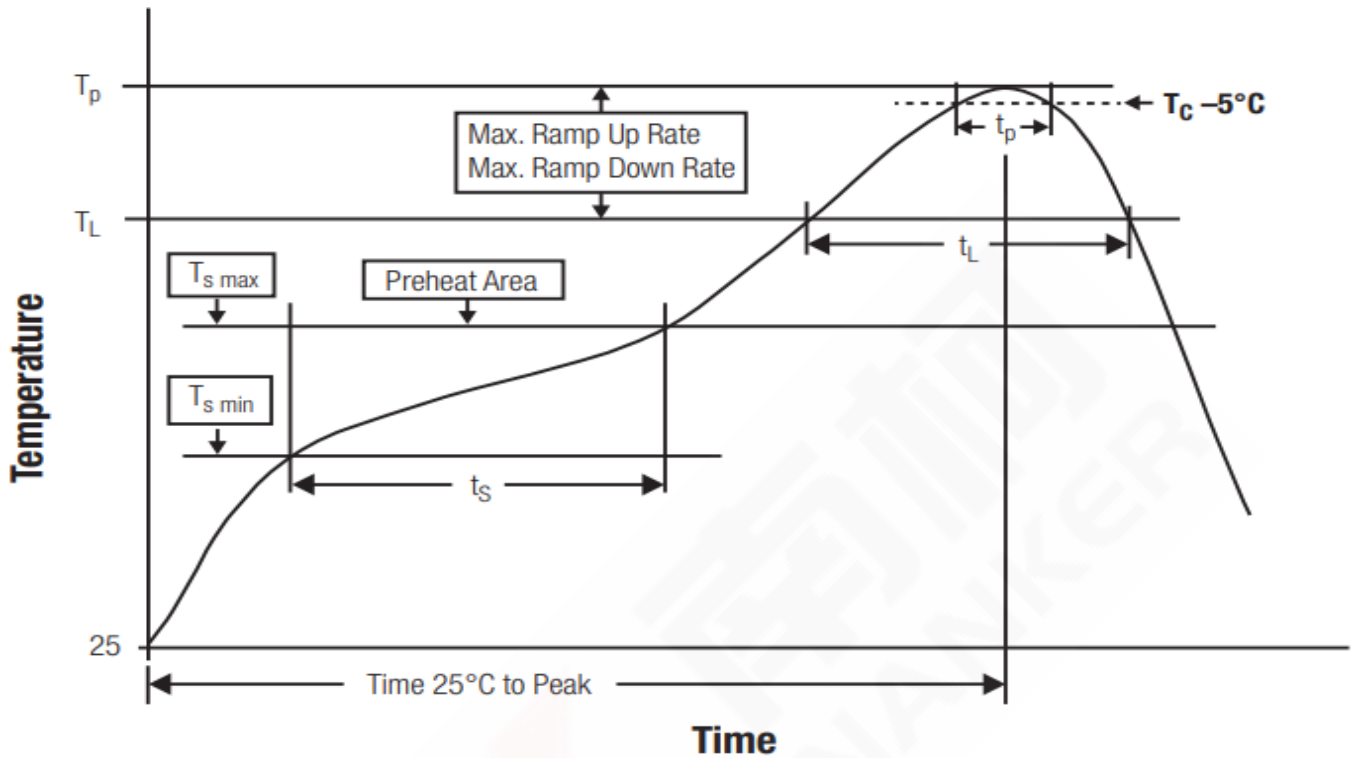
DCCM03-1210-2R0A





回流焊曲线图

Classification Reflow Profile for SMT Components



封装体峰值温度(Tp)分类

Classification Reflow Soldering Profile:

| | 封装厚度 Package Thickness | 封装体积 Package Volume | | |
|--------------------------|---------------------------|------------------------|---------------------------|------------------------|
| | | <350 mm ³ | 350~2,000 mm ³ | >2,000 mm ³ |
| 无铅装配 PB-Free Assembly | <1.60mm | 260°C | 260°C | 260°C |
| | 1.60~2.50mm | 260°C | 250°C | 245°C |
| | >2.50mm | 260°C | 245°C | 245°C |

- ◆ 回流焊参照标准 IPC/JEDEC J-STD-020D。
Reflow is refer to standard IPC/JEDEC J-STD-020D.